



ERI 2.0

ELECTRONICS
RESURGENCE
INITIATIVE

SUMMIT



Sung Kyu **Lim**

Program Manager


DARPA Microsystems Technology Office

Vision

Fully Automate Design,
Simulation, and Test of 3D
Heterogeneous Integrated
(HI) Systems

Mission

Create and Support 3DHI
Electronic Design
Automation (EDA) Programs
at DARPA MTO

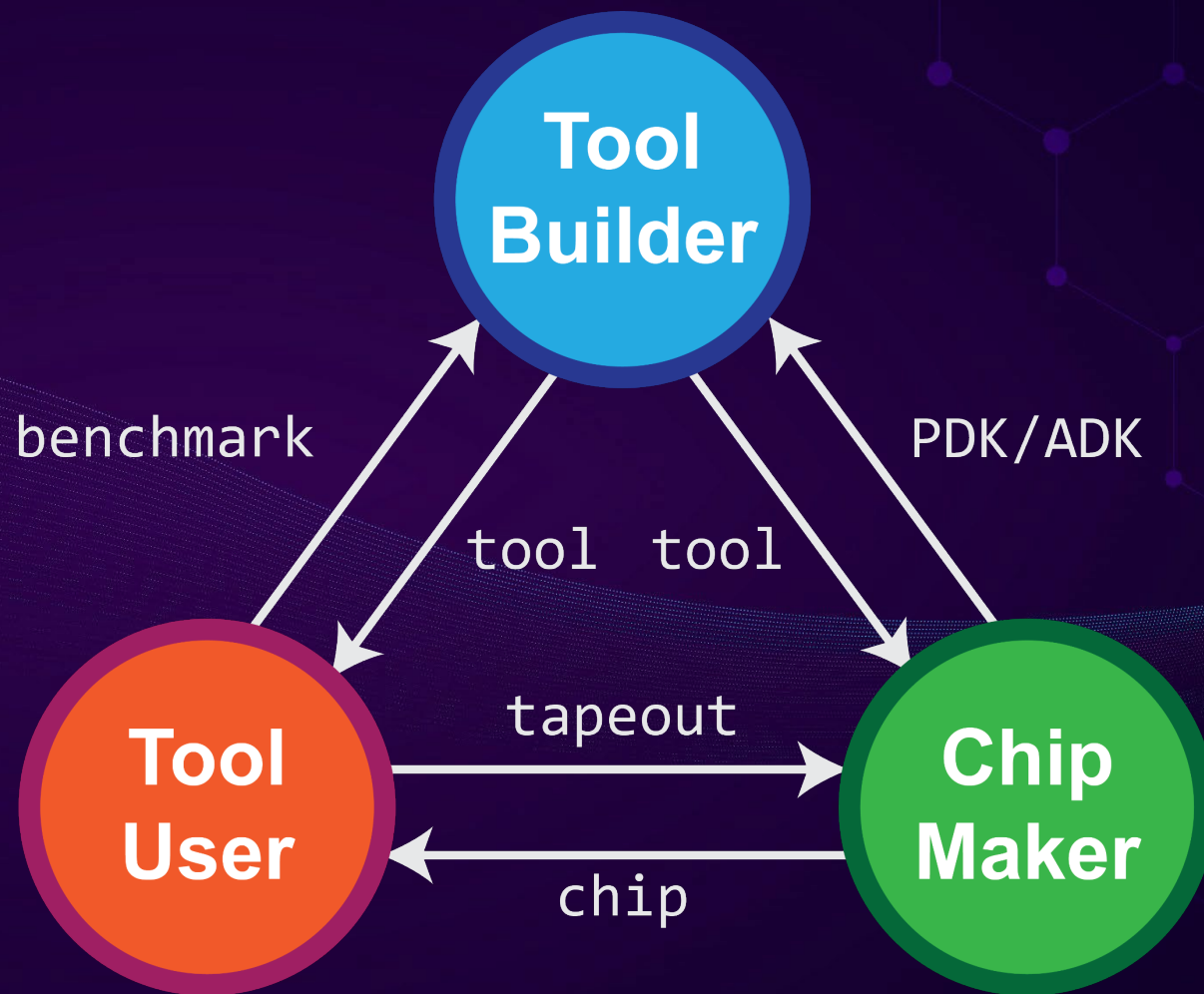


3D IC EDA: What is Needed, and How/When Can We Deliver?

3D IC EDA

It takes teamwork

- Tool Builder
- Tool User
- Chip Maker





Source: Samsung X-Cube

GOAL

Let us agree on a few things

- Tool users present
 - Pressing and future needs
 - Potential applications
- Tool builders discuss
 - Delivery roadmap
 - Grand challenges
- Reach an agreement on
 - Set of capabilities needed
 - Ways to facilitate communications

Meet Our Speakers

Timothy Lee
Boeing



Vincent Kim
Samsung



Pooya Tadayon
Intel



Elaine Tang
Siemens



Vinay Patwardhan
Cadence



Rob Aitken
Synopsys

